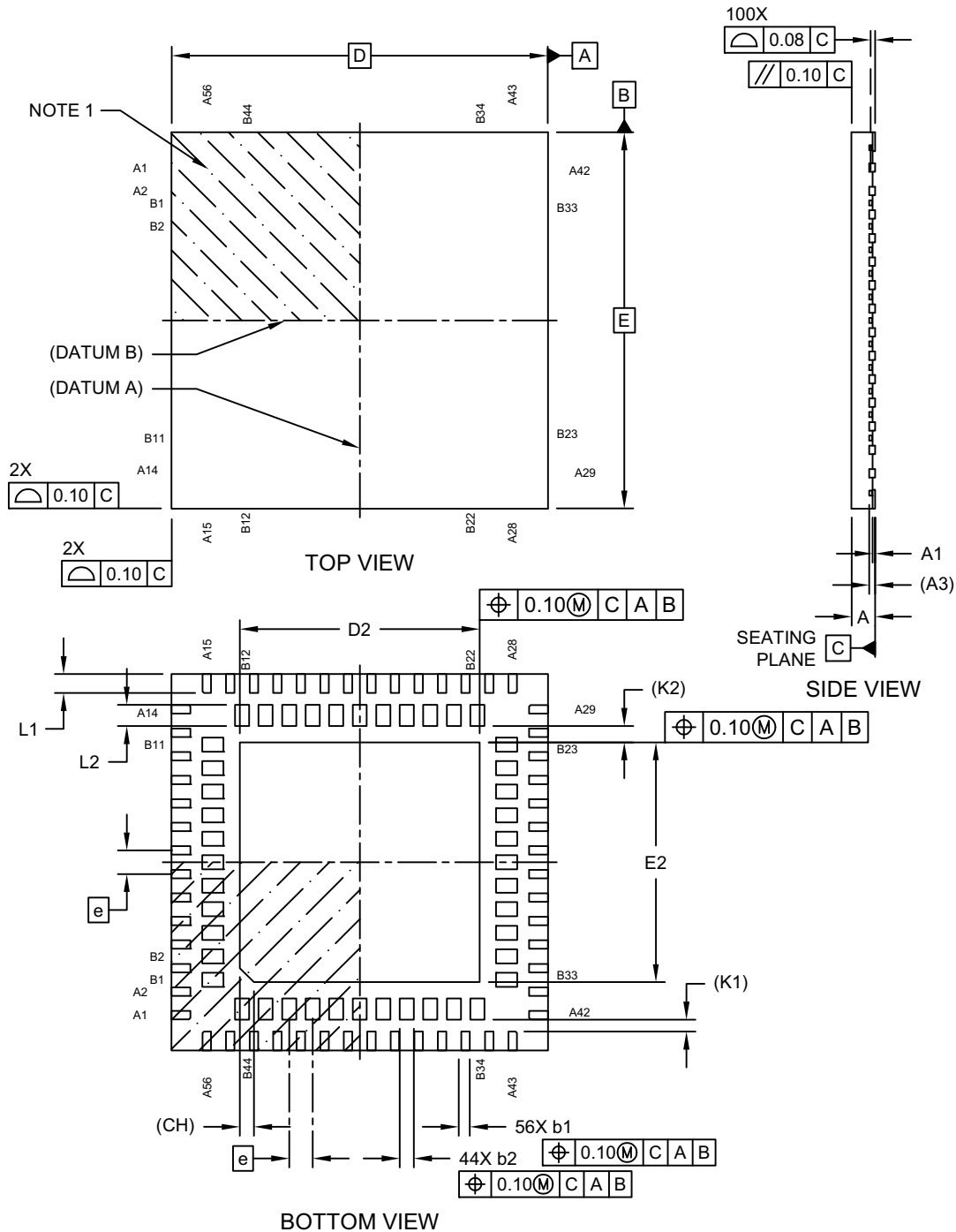


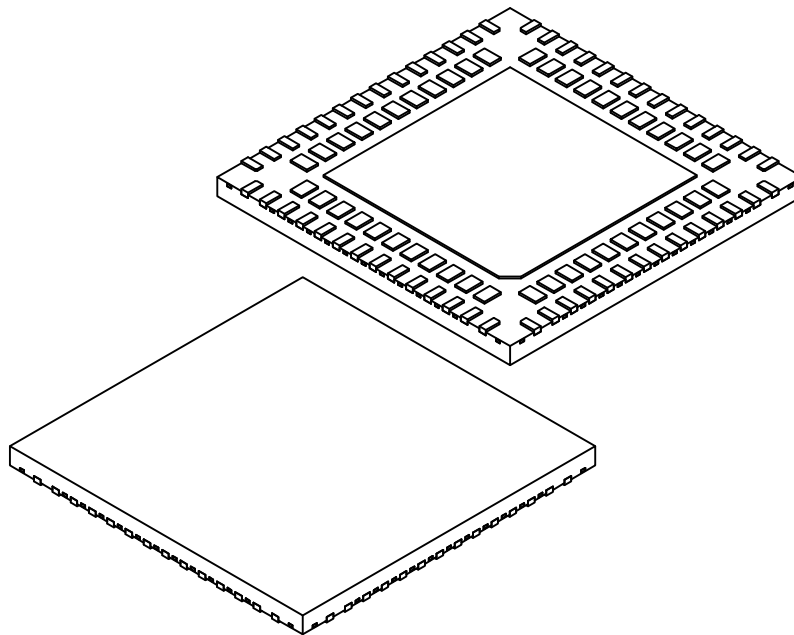
# 100-Lead Ultra Thin Quad Flat, No Lead Package (D4C) - 8x8X0.55 mm Body [UQFN] With Dual Terminal Rows and 5.10 Exposed Pad

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



# **100-Lead Ultra Thin Quad Flat, No Lead Package (D4C) - 8x8X0.55 mm Body [UQFN] With Dual Terminal Rows and 5.10 Exposed Pad**

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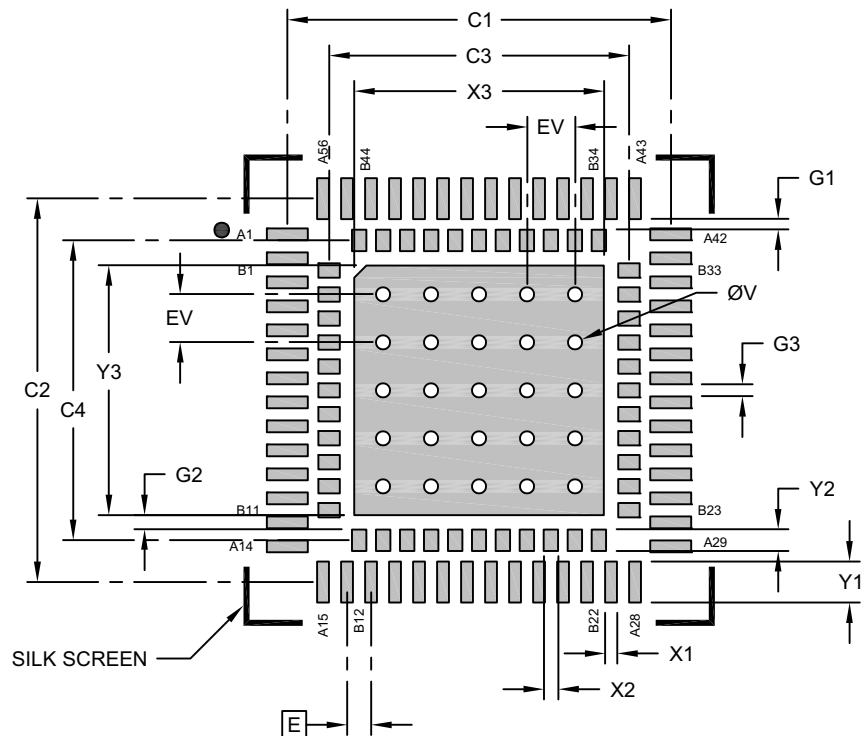
| Dimension Limits                 | Units | MILLIMETERS |      |      |
|----------------------------------|-------|-------------|------|------|
|                                  |       | MIN         | NOM  | MAX  |
| Number of Terminals              | N     | 100         |      |      |
| Pitch                            | e     | 0.50 BSC    |      |      |
| Overall Height                   | A     | 0.45        | 0.50 | 0.55 |
| Standoff                         | A1    | 0.00        | 0.02 | 0.05 |
| Terminal Thickness               | A3    | 0.127       |      |      |
| Overall Length                   | D     | 8.00 BSC    |      |      |
| Exposed Pad Length               | D2    | 5.00        | 5.10 | 5.20 |
| Overall Width                    | E     | 8.00 BSC    |      |      |
| Exposed Pad Width                | E2    | 5.00        | 5.10 | 5.20 |
| Outer Terminal Width             | b1    | 0.13        | 0.18 | 0.23 |
| Inner Terminal Width             | b2    | 0.25        | 0.30 | 0.35 |
| Outer Terminal Length            | L1    | 0.35        | 0.40 | 0.45 |
| Inner Terminal Length            | L2    | 0.40        | 0.45 | 0.50 |
| Outer Terminal to Inner Terminal | K1    | 0.25 REF    |      |      |
| Inner Terminal-to-Exposed-Pad    | K2    | 0.35 REF    |      |      |
| Exposed Pad Index Chamfer        | CH    | 0.30 REF    |      |      |

**Notes:**

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated
- Dimensioning and tolerancing per ASME Y14.5M
  - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
  - REF: Reference Dimension, usually without tolerance, for information purposes only.

# 100-Lead Ultra Thin Quad Flat, No Lead Package (D4C) - 8x8X0.55 mm Body [UQFN] With Dual Terminal Rows and 5.10 Exposed Pad

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

|                                    | Units | MILLIMETERS |          |      |
|------------------------------------|-------|-------------|----------|------|
|                                    |       | MIN         | NOM      | MAX  |
| Dimension Limits                   | E     |             | 0.50 BSC |      |
| Contact Pitch                      | E     |             |          |      |
| Center Pad Width                   | X3    |             |          | 5.20 |
| Center Pad Length                  | Y3    |             |          | 5.20 |
| Contact Pad Spacing Outer Row      | C1    |             | 7.99     |      |
| Contact Pad Spacing Outer Row      | C2    |             | 7.99     |      |
| Contact Pad Spacing Inner Row      | C3    |             | 6.246    |      |
| Contact Pad Spacing Inner Row      | C4    |             | 6.246    |      |
| Contact Pad Width Outer Row (X56)  | X1    |             |          | 0.25 |
| Contact Pad Length Outer Row (X56) | Y1    |             |          | 0.85 |
| Contact Pad Width Inner Row (X44)  | X2    |             |          | 0.30 |
| Contact Pad Length Inner Row (X44) | Y2    |             |          | 0.45 |
| Contact Pad to Center Pad          | G1    | 0.22        |          |      |
| Contact Pad to Contact Pad         | G2    | 0.30        |          |      |
| Contact Pad to Contact Pad         | G3    | 0.25        |          |      |
| Thermal Via Diameter               | V     |             | 0.30     |      |
| Thermal Via Pitch                  | EV    |             | 1.00     |      |

**Notes:**

- Dimensioning and tolerancing per ASME Y14.5M  
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process